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(54) Title: YIELD IMPROVEMENTS IN STACKED PACKAGING

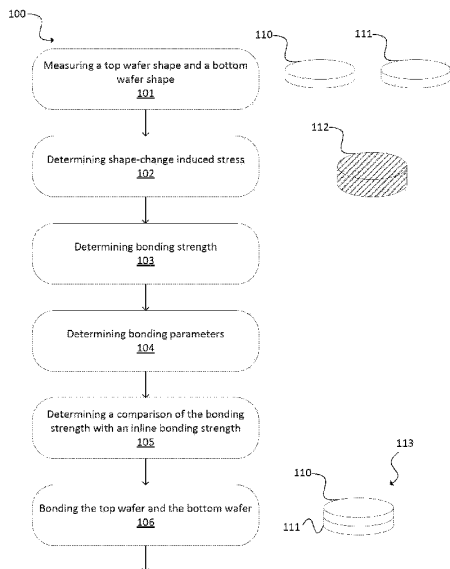


FIG. 1

(57) Abstract: Shape-changed induced stress for a target thickness of a bonded wafer can be determined. A bonding strength for the bonded wafer can then be determined using the shape-changed induced stress. Bonding parameters can be determined for the bonding strength. The bonding strength that is determined can be compared with an inline bonding strength for formation of the bonded wafer.

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